In the Claims

Claims 1-11 (Canceled).

12 (Original). A packaged electronic device comprising:

a microelectromechanical switch including a first surface having a cantilevered switch element;

a film bulk acoustic resonator having a first surface having upper and lower electrodes and a piezoelectric film formed thereon;

said switch and said resonator arranged with said first surfaces in opposition to one another; and

a sealing ring between said surfaces to define a chamber between said switch and said resonator.

13 (Original). The device of claim 12 including electrical contacts between said switch and said resonator extending through said chamber.

14 (Original). The device of claim 12 wherein said resonator includes a cavity in a second surface of said resonator, said cavity being covered by a substrate.

15 (Original). The device of claim 12 including contacts extending from the exterior of said device through said resonator to contact at least one of said electrodes.

16 (Original). The device of claim 12 including contacts that extend from the exterior of said device through said switch to make electrical contact with said switch on its first surface.

17 (Original). The device of claim 12 wherein said resonator has tapered exterior conductive surfaces that make electrical contact with said electrodes.

18 (Original). A semiconductor assembly comprising:

a first wafer including a microelectromechanical switch formed thereon on a first face of said first wafer;

a second wafer with a film bulk acoustic resonator formed on a first face of said second wafer; and

said wafers connected in first face-to-first face alignment.

19 (Original). The assembly of claim 18 including a sealing material around the first faces of said wafers to define a hermetically sealed chamber between said wafers.

20 (Original). The assembly of claim 18 wherein said second wafer includes a backside cavity and a third wafer formed over said backside cavity.

21 (Original). The assembly of claim 18 including a conductive contact extending between said film bulk acoustic resonator and said microelectromechanical switch.

22 (Original). The assembly of claim 18 further including a contact extending from the exterior of said assembly through said wafer with said film bulk acoustic resonator to make contact electrically with said film bulk acoustic resonator.

23 (Original). The assembly of claim 18 including a contact on the exterior of said assembly and extending through said wafer with said microelectromechanical switch.

24 (Original). The assembly of claim 18 including a notch formed in said film bulk acoustic resonator to enable electrical connection from the outside world to said film bulk acoustic resonator.